Intel® Core™2 Duo Processor E8300

6M Cache, 2.83 GHz, 1333 MHz FSB

Specifications

Export specifications

Essentials

Product Collection	Legacy Intel® Core™2 Processor
Code Name	Products formerly Wolfdale
Vertical Segment	Desktop
Processor Number	E8300
Status	End of Interactive Support
Launch Date	Q2'08
Lithography	45 nm
Recommended Customer Price	N/A
erformance	
# of Cores	2
Processor Base Frequency	2.83 GHz
Cache	6 MB L2
Bus Speed	1333 MHz FSB
FSB Parity	No
TDP	65 W
VID Voltage Range	0.8500V-1.3625V
upplemental Information	
Embedded Options Available	No
Datasheet	View now

Package Specifications

Sockets Supported	LGA775
T _{CASE}	72.4°C
Package Size	37.5mm x 37.5mm
Processing Die Size	107 mm ²
# of Processing Die Transistors	410 million
Low Halogen Options Available	See MDDS
dvanced Technologies	
Intel® Turbo Boost Technology ‡	No
Intel® Hyper-Threading Technology ‡	No
Intel® Virtualization Technology (VT-x) [‡]	Yes
Intel® Virtualization Technology for Directed I/O (VT-d)‡	Yes
Intel® 64 [‡]	Yes
Instruction Set	64-bit
Idle States	Yes
Enhanced Intel SpeedStep® Technology	Yes
Intel® Demand Based Switching	No
Thermal Monitoring Technologies	Yes
ntel® Data Protection Technology	
Intel® AES New Instructions	No
ntel® Platform Protection Technology	
Trusted Execution Technology ‡	Yes

Ordering and Compliance

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2635QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.

‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading/hyper-threading-technology.html? wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology. See www.intel.com/technology/turboboost/ for more information.

The Recommended Customer Price ("RCP") is pricing guidance for Intel products. Prices are for direct Intel customers, typically represent 1,000-unit purchase quantities, and are subject to change without notice. Taxes and shipping, etc. not included. Prices may vary for other package types and shipment quantities, and special promotional arrangements may apply. If sold in bulk, price represents individual unit. Listing of these RCP does not constitute a formal pricing offer from Intel. Please work with your appropriate Intel representative to obtain a formal price quotation.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content/www/us/en/processors/processor-numbers.html for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.